

Part Number: 2508052027Z0

MULTI-LAYER CHIP BEAD



Fair-Rite offers a broad selection of cost effective multi-layer chip beads to suppress conducted EMI signals. Chip beads can be used in an array of devices such as cellular phones, computers, laptops, pagers, etc. The small package sizes accommodate automated placements and allow for a dense packaging of circuit boards.

Chip Beads are available in standard, high and GHz signal speeds.

[Recommended Soldering Profile](#)

Packaging Options:

-All multi-layer chip beads are supplied taped and reeled, if required bulk packed chip beads can be provided.

The suggested land patterns are in accordance to the latest revision of IPC-7351.

Weight: 0.01 (g)

Package Size: 0805 (2012)

Dim	mm	mm tol	nominal inch	inch misc.
A	0.9	±0.20	0.035	—
B	1.25	±0.20	0.049	—
C	2	±0.20	0.079	—
D	0.5	±0.30	0.02	—

Reel Information				
Tape Width mm	Pitch mm	Parts 7" Reel	Parts 13" Reel	Parts 14" Reel
8	4	4000	10000	—


Land Patterns 				
V	W	X	Y	Z
0.60 (0.024")	1.90 (0.075")	1.50 (0.059")	1.30 (0.051")	-

Chart Legend

+ Test frequency

Typical Impedance (Ω)	
50 MHz	460
100 MHz ⁺	2000 \pm 25%
500 MHz	330
1000 MHz ⁺	-

Electrical Properties	
Max DCR (Ω)	0.4
Max Current (mA)	200

The impedance values listed are typical values. The nominal impedance with a +/- 25% tolerance is specified for the + marked 100 MHz. Chip beads are measured for impedance on the HP 4291A and fixture HP 16192A.

Chip beads are 100% tested for impedance and dc resistance.

Typical Impedance (Ω)	
50 MHz	440
100 MHz ⁺	2000 \pm 25%
500 MHz	160
1000 MHz ⁺	-



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